## **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listing, of claims in the application:

1 1. (Amended) A method of self-calibrating and testing the vaporized flow of 2 a liquid precursor in a thin film vaporization system comprising the steps of: 3 providing a thin film vaporization system comprising stored liquid precursors in 4 tanks under pressure connected to a deposition chamber via a manifold which in turn is 5 connected to pipe lines emanating from each tank and coupled to own liquid flow 6 meters (LFMs) and injection valves (IVs); 7 activating a servo mechanism to pump down said deposition chamber to achieve 8 partial vacuum therein; 9 opening a downstream throttle valve (TV) for a carrier gas to flow through said 10 manifold to commence self-calibration wherein said carrier gas is a second helium 11 carrier gas; 12 a first timing to monitor a baseline self-calibrated pressure by a pre-determined 13 TV opening which correlates with the specified baseline pressure in said deposition 14 chamber; 15 a second timing to allow for the stabilization of carrier gas after throttling said TV 16 to a predetermined opening; 17 selecting a liquid precursor and its own said respective pipe line with said own 18 LFM and own IV connected to said deposition chamber via said manifold; 19 setting said own IV to a predetermined opening to start said liquid precursor to 20 flow;

Attorney Docket No.: N1085-90106 TSMC 2000-0903

21 setting said TV opening to a normal liquid precursor flow rate for film deposition; 22 a third timing to allow for liquid precursor flow to stabilize; 23 a fourth timing to allow vaporization of said liquid precursor in said deposition 24 chamber; 25 measuring final pressure in said deposition chamber; 26 stopping the flow of said precursor fluid; and 27 pumping down said deposition chamber to continue with said film deposition 28 pending the result of said pressure rise. 1 2. (Original) The method according to claim 1, wherein said tanks are 2 pressurized by helium gas. 1 3. (Original) The method according to claim 2, wherein said helium gas is 2 pressurized to between about 20 to 30 pounds per square inch gauge (psig). 1 4. (Original) The method according to claim 1, wherein said helium gas is 2 kept at room temperature. 1 5. (Original) The method according to claim 1, wherein said manifold has 2 heater elements. 1 (Original) The method according to claim 5, wherein said heated fixture 6. 2 elements are spaced nominally at 290 mils between about 250 to 350 mils from 3 distribution shower head. 1 7. (Original) The method according to claim 5, wherein said heated fixture is 2 heated nominally to 400° C between about 350 to 450° C. 1 8. (Canceled)

Appl. No. 10/082,024 Attorney Docket No.: N1085-90106 Amdt. dated 11/17/04 TSMC 2000-0903

1 9. (Amended) The method according to claim 1, wherein flow of said second

helium carrier gas through said manifold is between about 750 to 850 milligrams per

3 minute (mgm).

2

- 1 10. (Original) The method according to claim 1, wherein said first timing is
- 2 between about 5 to 15 seconds.
- 1 11. (Original) The method according to claim 1, wherein said baseline self-
- 2 calibrated pressure is between about 2 to 4 torr.
- 1 12. (Original) The method according to claim 1, wherein said second timing is
- 2 between about 4 to 6 seconds.
- 1 13. (Original) The method according to claim 1, wherein said liquid precursor
- 2 is tetraethylorthosilicate (TEOS).
- 1 14. (Original) The method according to claim 1, wherein said liquid precursor
- 2 is triethylborate (TEB).
- 1 15. (Original) The method according to claim 1, wherein said liquid precursor
- 2 is tri-ethylphosphate (TEPO).
- 1 16. (Original) The method according to claim 1, wherein said injection valve
- 2 (IV) comprises a venturi tube.
- 1 17. (Previously Presented) The method according to claim 1, wherein said
- 2 normal liquid precursor flow rate is between 800 to 1000 milligram per minute (mgm).
- 1 18. (Original) The method according to claim 1, wherein said third timing to
- 2 allow for liquid precursor to stabilize is between about 7 to 9 seconds.
- 1 19. (Original) The method according to claim 1, wherein said fourth timing to
- 2 allow for liquid precursor vaporized flow to be verified is between about 4 to 6 seconds.

Appl. No. 10/082,024 Attorney Docket No.: N1085-90106 Amdt. dated 11/17/04 TSMC 2000-0903

1 20. (Original) The method according to claim 1, wherein said final pressure in 2 said deposition chamber is between about 6.5 and 7.5 torr.

- 1 21. (Original) The method according to claim 1, wherein said pumping down
- 2 said deposition chamber is accomplished within between about 9 to 11 seconds.
- 1 22-31. (Canceled)